## DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the inventor entitled: "Etching Processes for Integrated Circuit Manufacturing Including Methods of Forming Capacitors", the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

## PRIOR FOREIGN APPLICATIONS:

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statement may jeopardize the validity of the application or any patent issued therefrom.

	$\sim$ $\Lambda$			
Full name of inventor:	Paul A. Morgan			
Inventor's Signature:	1 20 m			
Date:	9/8/02			
Residence:	Kuna, Idano			
Citizenship:	United States of America			
Post Office Address:	12768 South Cloverdale Road, Kuna, ID 83634			
	* * * * * * * * * *			
Full name of inventor:	Patrick M. Flynn			
Inventor's Signature:	Potel M. Ty			
Date:	2/8/2002			
Residence:	Boise, Idaho			
Citizenship:	United States of America			
Post Office Address:	8809 West Donnybrook Drive, Boise, ID 83709			
	* * * * * * * * * *			
Full name of inventor:	Janos Fucsko			
Inventor's Signature:	Janos Fucko			
Date:	2/11/2002			
Residence:	Boise, Idaho			
Citizenship:	Hungary			
Post Office Address:	1634 Martha Street, No. 101, Boise, ID 83709			

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No
Application Serial No
tan
Assignee Micron Technology, Inc.
Assignee
Assignee
Examiner
Attorney's Docket No
Fitle: Etching Processes for Integrated Circuit Manufacturing including Methods of
Forming Capacitors

## POWER OF ATTORNEY BY ASSIGNEE AND CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(b)

To: Assistant Commissioner for Patents

Washington, D.C. 20231

Sir:

MICRON TECHNOLOGY, INC., the Assignee of the entire right, title and interest in the above-identified patent application by assignment attached hereto, hereby appoints the attorneys and agents of the firm of WELLS ST. JOHN P.S., listed as follows:

David P. Roberts Randy A. Gregory Mark S. Matkin James L. Price Deepak Malhotra Mark W. Hendricksen David G. Latwesen George G. Grigel Keith D. Grzelak James D. Shaurette Frederick M. Fliegel D. Brent Kenady James E. Lake Bernard Berman	Reg. Reg. Reg. Reg. Reg. Reg. Reg. Reg.	No.	23,032 30,386 32,268 27,376 33,560 32,356 38,533 31,166 37,144 39,833 36,138 40,045 44,854 37,279 48,711
Jennifer J. Taylor	Reg.	NO.	48,711

and also attorneys Michael L. Lynch (Reg. No. 30,871) and Charles B. Brantley II (Reg. No. 38,086) of Micron Technology, Inc., as its attorneys with full power of substitution to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

The Assignee certifies that the above-identified Assignment has been reviewed and to the best of Assignee's knowledge and belief, title is in the Assignee, and a copy of the Assignment is submitted herewith.

Please direct all correspondence regarding this application to:

Customer No. 021567 Wells St. John P.S. Attn: Mark S. Matkin

601 West First Avenue, Suite 1300

Spokane, WA 99201-3828 Telephone: (509) 624-4276 Facsimile: (509) 838-3424

MICRON TECHNOLOGY, INC.

Dated: \_\_\_\_\_\_\_\_\_

By:

Name: Roderic W. Lewis

Title: Vice President, Legal, General

Counsel and Corporate Secretary

Attachment: Copy of Assignment